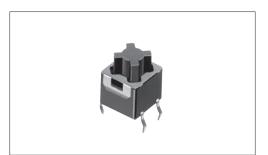
F Long-travel with High Operation Force (Snap-in Type)

8×9mm size. Combination of long travel 1.75mm and high operation force prevents malfunction







■ Typical Specifications

Items	Specifications	
Rating (max.)	5mA 12V DC	
Rating (min.)	10 μA 1V DC	
Initial contact resistance	1kΩ max.	
Travel (mm)	1.75	

■ Product Line

Product No.	Operating force	Operating direction	Operating life (5mA 5V DC)	Minimum order unit (pcs.)		
T TOUGGE TWO.	Operating force	Operating torce Operating direction		Japan	Export	
SKPFACA010	1.96N	Top push	100,000 cycles	1,000	1,000	
SKPFAAA010	3.92N	τορ ρασιτ				

■ Packing Specifications

Bulk

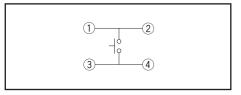
Number of pa	Export package measurements		
1 case / Japan	1 case / export packing	(mm)	
4,000	12,000	309×476×347	

Dimensions

Unit:mm

Style	PC board mounting hole dimensions (Viewed from switch mounting face)
8 8 8 8 8 7 0.7 4.5	8.7 4-ø1 hole

Circuit Diagram



Note

Please Using a 1.6mm thick PC board is recommended.

	Type				Sc	oft Feeling Ty	he			
	Туре		Snap-in			Surface	Mount		Ra	dial
	Series	SKEG	SKEG	SKPF	SKPS	SKPM	SKPG	SKPR	SKPL	SKPD
	Photo			8	NEW			9		Ø:
F	eatures	_	_	High operation force Long travel	Low contact resistance	Low contact resistance	_	High operation force Low contact resistance	Round terminal Low contact resistance	_
Wa	ater-proof	_	_	_	_	_	_	_	_	_
Di	ust-proof	_	_	_	_	_	_	_	_	_
IP	standard	_	_	_	_	_	_	_	_	_
Operating	Top push	•	_	•	•	•	•	•	•	•
direction	Side push	_	•	_	_	_	_	_	_	_
	W		7.5	8	5	.9	6.6	7.5		
Dimension (mm)	D D	□6	9.9	9	6	3	6.3	7.8	φ 6.45	□7.8
(111111)	Н	See the relevant pages for respective product descriptions	7.3	10		5		6.5	5	See the relevant pages for respective product descriptions
(Contact		Carbon		Sil	ver	Carbon	Sil	ver	Carbon
Operation force coverage	2N to 3N	1	1	1	+	Ţ	Ţ		1	
00101480	4N to 5N			See the relevant pages				\$		See the relevant pages
Tra	avel (mm)	1		for respective product descriptions	1.05	1.	3	1	1.3	for respective product descriptions
Ground terminal		_	_	_	_	_	_	_	_	_
Operatir	ng temperature range	-20°C to	o +70℃		-40°C to +90°C					
Auto	motive use	•	•	•	•	•	•	•	•	•
Li	ife Cycle	* 2	2	2	* 2	*3	*3	*3	* 2	* 2
	Rating (max.) (Resistive load)	5	5mA 12V D(0	50mA 5mA 16V DC 12V DC					5mA 12V DC
Electrical	Rating (min.) (Resistive load) 10 µA 1V DC									
performance	Insulation resistance			1	00MΩ min. 1	00V DC 1mir	٦.			50MΩ min. 100V DC 1min. SKPDAF: 100MΩ min. 100V DC 1min.
	Voltage proof				250V A	C 1min.				100V AC 1min. SKPDAF: 250V DC 1min.
Durability Vibration 10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively Shall be in accordance with individual specifications.		ies,								
		ations.								
	Cold	-30°	C 96h	-40℃ 96h	-40℃	1,000h	-40°C 96h	-40℃	1,000h	-40°C 96h
Environmental performance	Dry heat	80℃	96h	90℃ 96h	90°C 1	,000h	90℃ 96h	90°C	I,000h	90℃ 96h
	Damp heat	60°C, 9	90 to 95%F	H 96h 60°C, 90 to 95%RH 1,000h			60°C, 90 to 95%RH 96h		to 95%RH DOh	60°C, 90 to 95%RH 96h
	Page	25	56	258	259	260	261	262	263	264

W: Width. The most outer dimension excluding terminal portion.

Notes

^{2.} \blacksquare Indicates applicability to all products in the series.



D : Depth. The most outer dimension excluding terminal portion.

 $[\]ensuremath{\mathsf{H}}$: Height. The minimum dimension if there are variances.

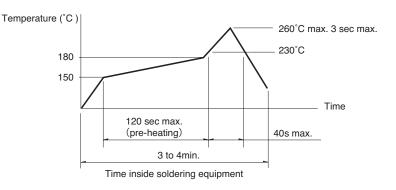
^{1.} The automotive operating temperature range to be individually discussed upon request.

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
 The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

Manual Soldering

Items		Condition
Soldering temperature		350℃ max.
Duration of soldering		3s max.
	Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

